

CERTIFICATE OF MAILING BY "EXPRESS MAIL" (37 CFR 1.10)Applicant(s): **Sudhakar BOBBA et al.**

Docket No.

03226/147001; P6841

Serial No.

09/997,438

Filing Date

November 29, 2001

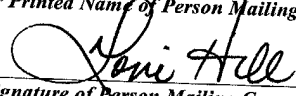
Examiner

L. Cruz

Group Art Unit

2827Invention: **150 DEGREE BUMP PLACEMENT LAYOUT FOR AN INTEGRATED CIRCUIT POWER GRID**I hereby certify that this **Reply Under 37 CFR 1.116 with Substitute Specification***(Identify type of correspondence)*

is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 in an envelope addressed to: The Commissioner of Patents and Trademarks, Washington, D.C.

20231-0001 on **March 7, 2003***(Date)***Toni Hill***(Typed or Printed Name of Person Mailing Correspondence)*
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3-1003

AP/2825

AMENDMENT TRANSMITTAL LETTER (Large Entity)

Applicant(s): **Sudhakar BOBBA et al.**

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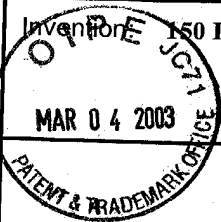
Filing Date
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Group Art Unit
2827

Inventor: **150 DEGREE BUMP PLACEMENT LAYOUT FOR AN INTEGRATED CIRCUIT POWER GRID**

MAR 04 2003



TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	22 -	22 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	4 -	4 =	0 x	\$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

- ☒ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of _____
- ☐ A duplicate copy of this sheet is enclosed.
- ☐ A check in the amount of _____ to cover the filing fee is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. **50-0591**
- A duplicate copy of this sheet is enclosed.
- ☒ Any additional filing fees required under 37 C.F.R. 1.16.
- ☒ Any patent application processing fees under 37 CFR 1.17.

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Dated: **3/7/03**

Signature

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U.S. PATENT APPLICATION NO. 09/997,438
ATTORNEY DOCKET NO.: 03226.147001/P6841

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Sudhakar BOBBA et al.
Serial No.: 09/997,438
Filed : November 29, 2001
Title : 150 DEGREE BUMP PLACEMENT LAYOUT FOR AN INTEGRATED
CIRCUIT POWER GRID

Art Unit : 2827
Examiner : Lourdes CRUZ

Assistant Commissioner for Patents
Washington, DC 20231

REPLY UNDER 37 CFR § 1.116

Dear Sir:

In response to the final Office Action dated January 24, 2003, please amend the application as follows and consider the included remarks.

IN THE CLAIMS:

Please amend claims 1, 6, 11, and 17 as follows [a marked-up copy of the amended claims is provided in Appendix A]:

- 1 (Twice Amended) An integrated circuit having a top metal layer, the top metal layer having a first metal bar and a second metal bar, the integrated circuit comprising:
- a first bump disposed on the first metal bar;
 - a second bump disposed on the first metal bar, wherein the second bump is adjacent to the first bump; and
 - a reference bump disposed on the second metal bar,
- wherein the first bump and the second bump are positioned such that an angle between a line from the reference bump to the first bump and a line from the reference bump to the second bump has a value substantially equal to 150 degrees.
- 6 (Twice Amended) An integrated circuit having a top metal layer, the top metal layer having a first metal bar and a second metal bar, the integrated circuit comprising:
- a first bump disposed on the first metal bar;

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